



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moden et al.

Serial No.: 09/942,323

Filed: August 29, 2001

For: METHOD FOR APPLYING ADHESIVES TO A LEAD FRAME (as

amended)

Confirmation No.: 9742

Examiner: H. Lee

Group Art Unit: 2823

Attorney Docket No.: 2269-3089.2US

(96-0734.02/US)

Notice of Allowance Mailed:

April 1, 2003

Express Mail Mailing Label No.:

EV 348044940 US

Date of Deposit with USPS:

June 27, 2003

Person making Deposit:

Matthew Wooton

TRANSMITTAL LETTER

Mail Stop Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Applicants submit herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1,615.00 in payment for the issue fee, the publication fee, and five (5) copies of the patent when issued.

Also, enclosed is an Amendment Pursuant to 37 C.F.R. § 1.312(a) (85 pages), plus attached Replacement Drawing (1 sheet) and second copy of March 17, 2003 Supplemental

Information Disclosure Statement, PTO-1449, and USPTO date-stamped postcard; Comments on Statement of Reasons for Allowance(4 pages); and Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages).

Applicants understand that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,

Joseph A. Walkowski Registration No. 28,765 Attorney for Applicant(s)

TRASKBRITT P.O. Box 2550

Salt Lake City, Utah 84110-2550

Telephone: 801-532-1922

Date: June 27, 2003

JAW/ps:ljb

7.7

Enclosures: Part B - Issue Fee Transmittal

Check No. 19065 in the amount of \$1,615.00

Copy of Transmittal Letter

Amendment Pursuant to 37 C.F.R. § 1.312(a) (85 pages)

Replacement Drawing (1 sheet)

Second copy of March 17, 2003 Supplemental Information Disclosure Statement,

PTO-1449, and USPTO date-stamped postcard

Comments on Statement of Reasons for Allowance(4 pages)

Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)

Document in ProLaw

Complete and sand this form, together with applicable fee(s), to: Mail Box ISSUE FEE
Commissioner for Patents
Washington, D.C. 20231
Fax (703)746-4000

INSTRUCTIONS: This before should be used for transmitting the ISSUE FEE and PUBLICATION FEE (if required). Blocks 1 through 4 should be completed where appropriate. All further defrespondence including the Patent, advance orders and notification of maintenance fees will be maited to the current correspondence address as indicated unless correctly below or directed otherwise in Block 1, by (a) specifying a new correspondence address; and/or (b) indicating a separate "FEE ADDRESS" for maintenance fee notifications.

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SALT LAKE CITY, UT 84110

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APPLICATION NO.			OR	ATTORNEY	DOCKET NO.	CONFIRMATION NO	
09/942,323	·		Walter L. Moden		3089.2US	(96-0734.2)	9742
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APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLIC	ATION FEE	TOTAL FEE	(S) DUE	DATE DUE
nonprovisional	NO	\$1300		300	\$160	00	07/01/2003
EXAMINER		ART UNIT CLASS-SUBCLASS		ss			
LEE, HSIEN MING		2823	2823 438-015000				
1. Change of correspondence address or indication of "Fee Address CFR 1.363). 1. Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached. 2. "Fee Address" indication (or "Fee Address" Indication form PTO/SB/47; Rev 03-02 or more recent) attached. Use of a Custo Number is required.			2. For printing on the patent from page, list (1) the names of up to 3 registered patent attorneys or agents OR, alternatively, (2) the name of a single furm (having as a member a registered attorney or agent) and the names of up to 2 registered patent attorneys or agents. If no name is listed, no name will be princed. 3 TraskBr			ritt	
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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In the Office Action dated October 15, 2002, the Examiner noted claims 34-65 were allowable and claims 5-8 and 10-33 would be allowable is rewritten in independent form. The Examiner stated:

The prior art of record, Moden (US 5,733,800), teaches the claimed method as recited in claims 1-4 and 9 as stated above, but at least neither teaches nor suggests: (1) biasing the semiconductor component downward proximate the

viscous material in the viscous material pool; (2) providing one of a hydraulic biasing mechanism, pneumatic biasing mechanism, and electrically powered biasing mechanism configurated to place the one semiconductor component proximate the viscous material; (3) raising the viscous material pool upward proximate the semiconductor component; (4) leveling the exposed surface of the viscous material prior to wetting a specific location of the semiconductor component; and (5) exposing the exposed surface of the viscous material, the exposed surface of the viscous material having a height that extends above the height of the at least one peripheral edge.

Applicants disagree with the statement that the Moden reference (US 5,733,800) teaches the claimed method as recited in claims 1-4 and 9. Applicants refer to the statements expressed during prosecution of the application herein and the subsequent allowability of claims 1-4 and 9.

Applicants concur with the remaining reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. Each of the independent claims include additional features and elements that are not addressed in the statement of reasons for allowance. Each of the dependent claims include further elements and features not addressed by the Examiner. Accordingly, the scope of the claims must be determined from each as a whole and equivalents therefrom. Furthermore, applicants have noted additional reasons for allowability during the prosecution of the application herein.

In the Notice of Allowability, the Examiner stated:

The prior art of record, Moden to US 5,733,800, in Figs. 2A-2B teaches a method for applying viscous material to at least one semiconductor component, the method comprising:

- providing a pool 36 (i.e. sprue) containing heated resin material 30, the heated resin material pool 36 shaped such that an exposed surface of the heated resin material 30 is located in a precise location (i.e. the bottom 38 of the pool 36) and including at least one upward facing opening (i.e. the opening facing a plunger 32), the at least upward facing opening exposing at least the exposed surface of the heated resin material 30 (Fig. 2A);
- melting the heated resin material 30 by forcing the plunger 32 downward to the pool 36 form a viscous resin material 30 (Fig. 2B); and

 forcing the viscous resin material 30 flowing through the bottom 38 of the pool 36 and into the cavity 44 of one semiconductor component 100.

In contrast, the prior art of record at least neither teaches nor suggests: (1) aligning at least one semiconductor component over the viscous material pool; (2) wetting a specific location of the at least one semiconductor component with the viscous material; (1) biasing the semiconductor component downward proximate the viscous material in the viscous material pool; (2) providing one of a hydraulic biasing mechanism, pneumatic biasing mechanism, and electrically powered biasing mechanism configurated to place the one semiconductor component proximate the viscous material; (3) raising the viscous material pool upward proximate the semiconductor component; (4) leveling the exposed surface of the viscous material prior to wetting a specific location of the semiconductor component; and (5) exposing the exposed surface of the viscous material, the exposed surface of the viscous material having a height that extends above the height of the at least one peripheral edge.

Therefore, the claimed invention is neither anticipated nor rendered obvious over the prior art of record.

With respect to the Examiner's characterization of Moden (U.S. 5,733,800), applicants refer to the arguments and statements made during prosecution of the application herein. Applicants agree with the Examiner's statement of reasons for allowance in so far as the reasons are exemplary and not comprehensive. Each of the independent claims include additional features and elements that are not addressed in the statement of reasons for allowance. Each of the dependent claims include further elements and features not addressed by the Examiner. Accordingly, the scope of the claims must be determined from each as a whole and equivalents therefrom. Furthermore, applicants have noted additional reasons for allowability during the prosecution of the application herein.

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Respectfully submitted,

Joseph A. Walkowski Registration No. 28,765 Attorney for Applicant(s)

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